ON Semiconductor®



				an frame California				
Title of Change:			WDFN10 Wire conversion from Gold wire to Palladium coated copper wire.					
Proposed First Ship date:			30 Jun 2021 or earlier if approved by customer					
Contact Information:			Contact your local ON Semiconductor Sales Office or <u>BernardRajVellangani.Pelevindran@onsemi.com</u>					
PCN Samples Contact:			Contact your local ON Semiconductor Sales Office or < <u>PCN.samples@onsemi.com</u> >. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.					
Type of Notification:			This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < <u>PCN.Support@onsemi.com</u> >					
Marking of Parts/ Traceability of Change:			Will carry date code marking "PZ" W21'2021 and above.					
Change Category:			Assembly Change					
Change Sub-Category(s):			Material Change					
Sites Affected:								
ON Semiconductor Sites			External Foundry/Subcon Sites					
ON Semiconductor Seremban, Malaysia			None					
Description and	d Purpose:							
			Before Change Des	cription	After Change Description			
Bond Wire 2		2.0	Omil Gold wire		2.0mil Palladium Coated Copper Wire			
There is no prod	luct marking change as	a result	of this change.					
Oualification P	lan:							
QV1 DEVICE NAI	ME: <u>NIS5021MT2TXG</u> N10 4.0*4.0*.75MM							
Test	Specification		Condition			Interval		
HTOL	TA=125C JA108	3	TA=125C, bias at 1.2X Nominal (not to exceed Max rate			1008 hrs		
HTRB	JESD22-A108		Tj = Max rate T	j for device, bias = 10	00% of rated V for Q 101 Rev D	1008 hrs		
HTSL	JESD22-A103			Ta =Max rate storage	2016 hrs			
PC	J STD 020 , JESD22-	A113	IR reflow at 260C					
HAST+PC	JESD22-A110		Temp = 130C, 85% RH, ~ 18.8 psig, bias = 100% of rated V or 100V max					
TC+PC	C JESD22-A104		Temp = -65°C to +150°C; for 1000 cycles (or equivalent)			1000 cyc		
UHAST+ PC JESD22-A118			Temp = 130C, RH=85%, ~ 18.8 psig					
UHAST+ PC	JESD22-A118			Temp = 130C, RH=85	5%, ~ 18.8 psig	96 hrs		

Estimated date for qualification completion: 31 May 2021

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List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle		
NIS5021MT1TXG	NIS5021MT2TXG		
NIS5020MT1TXG	NIS5021MT2TXG		
NIS5020MT2TXG	NIS5021MT2TXG		
NIS5820MT1TXG	NIS5021MT2TXG		
NIS5820MT2TXG	NIS5021MT2TXG		
NIS5021MT2TXG	NA		

Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NIS5021MT1TXG		NIS5021MT2TXG	NA	
NIS5020MT1TXG		NIS5021MT2TXG	NA	
NIS5820MT1TXG		NIS5021MT2TXG	NA	
NIS5820MT2TXG		NIS5021MT2TXG	NA	
NIS5020MT2TXG		NIS5021MT2TXG	NA	
NIS5021MT2TXG		NA	NA	